

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field device integration (FDI<sup>®</sup>) –  
Part 8: EDD to OPC-UA Mapping**

**Intégration des appareils de terrain (FDI<sup>®</sup>) –  
Partie 8: Mapping de l'EDD avec l'OPC-UA**



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**Intégration des appareils de terrain (FDI®) –  
Partie 8: Mapping de l'EDD avec l'OPC-UA**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/851/CDV	65E/909/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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### Part 8: EDD to OPC-UA Mapping

#### 1 Scope

This part of IEC 62769 specifies how the internal view of a device model represented by the EDD can be transferred into an external view as an OPC-UA information model by mapping EDD constructs to OPC-UA objects.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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IEC 61804-3, *Devices and integration in enterprise systems – function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

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IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

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OPC 10000-17, *OPC Unified Architecture – Part 17: Alias Names*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

IEC 62541-100, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

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